

SURFACE MOUNT GLASS PASSIVATED BARRIER RECTIFIERS

REVERSE VOLTAGE - 100 to 1000 Volts
FORWARD CURRENT - 0.8 Amperes

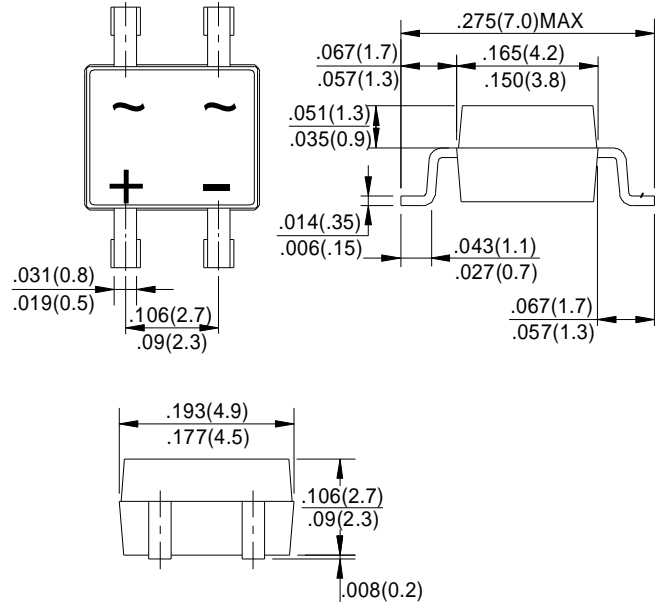
FEATURES

- Rating to 1000V PRV
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- Lead tin plated copper

MECHANICAL DATA

- Polarity: Symbol molded on body
- Weight: 0.0044 ounces, 0.125 grams
- Mounting position : Any

MBS



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave ,60Hz, resistive or inductive load.

For capacitive load, derate current by 20%

CHARACTERISTICS	SYMBOL	RH101	RH102	RH103	RH104	RH105	UNIT
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	100	200	400	600	800	V
Maximum RMS Voltage	V _{RMS}	70	140	280	420	560	V
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	V
Maximum Average Forward Rectified Current (Note 1) @T _A =40°C	I _(AV)	0.8					A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load(JEDEC Method)	I _{FSM}	40					A
Peak Forward Voltage at 0.8A DC	V _F	1.15					V
Maximum DC Reverse Current @T _J =25°C at Rated DC Blocking Voltage @T _J =125°C	I _R	5.0					uA
I ² t Rating for Fusing (t<8.3ms)	I ² t	3.7					A ² s
Maximum Reverse Recovery Time	T _{RR}	150		250		500	nS
Typical Junction Capacitance Per Element (Note2)	C _J	13					pF
Typical Thermal Resistance (Note3)	R _{θJC}	75					°C/W
Operating Temperature Range	T _J	-55 to +150					°C
Storage Temperature Range	T _{STG}	-55 to +150					°C

NOTES:1.Mounted on P.C. board.

2.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

3.Thermal resistance junction to ambient.

FIG.1-FORWARD CURRENT DERATING CURVE

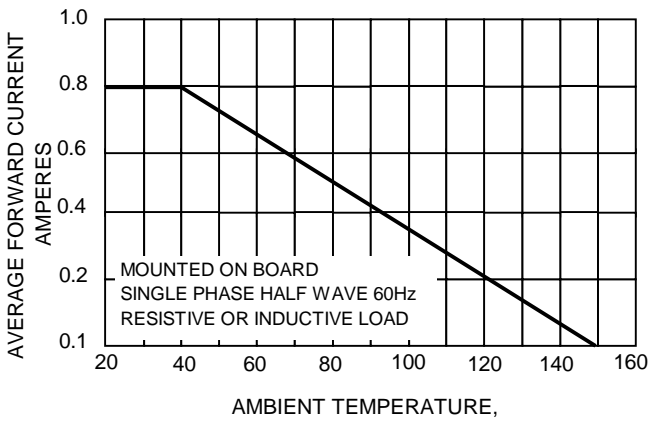


FIG.2-MAXIMUM NON-REPETITIVE SURGE CURRENT

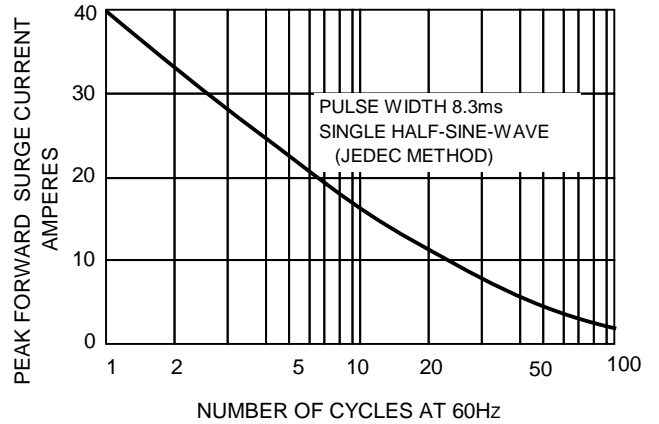


FIG.3-TYPICAL REVERSE CHARACTERISTICS

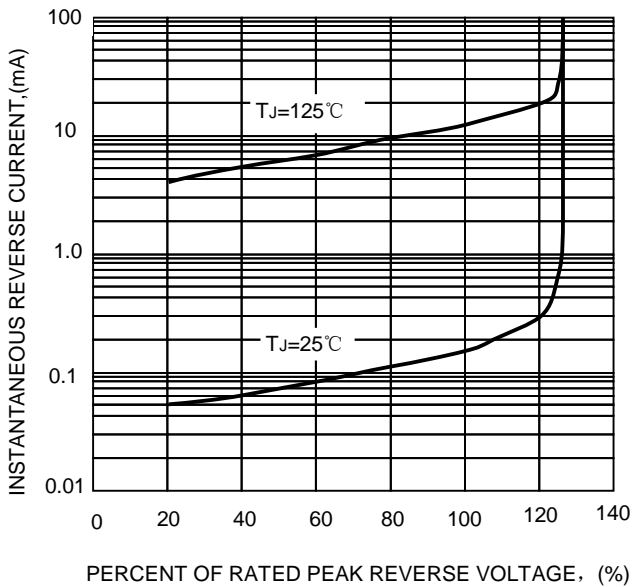


FIG.4-TYPICAL FORWARD CHARACTERISTICS

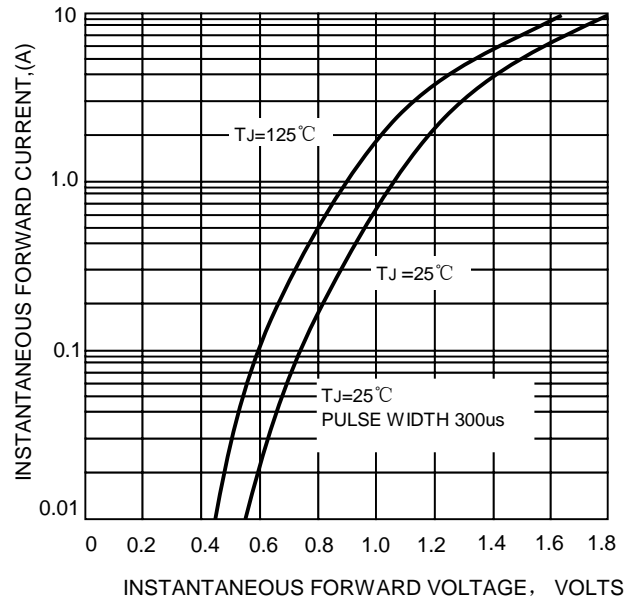


FIG.5-TYPICAL JUNCTION CAPACITANCE

